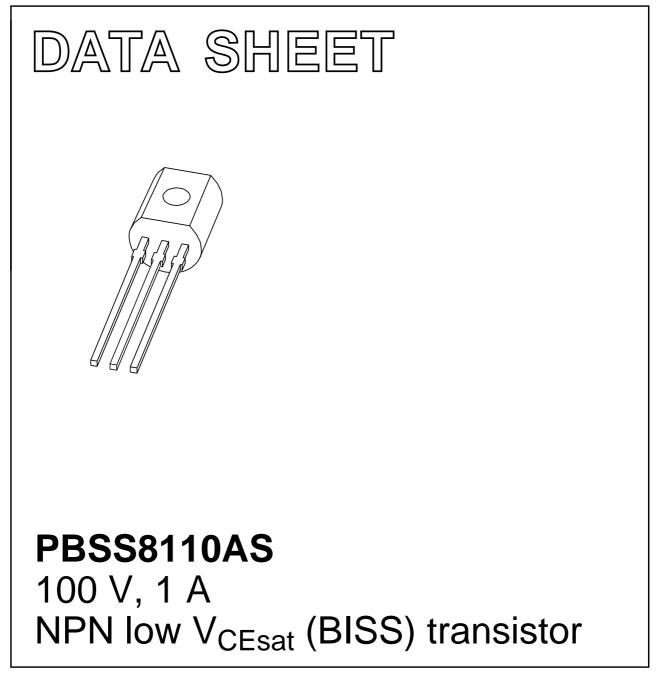
DISCRETE SEMICONDUCTORS



Product specification Supersedes data of 2003 Dec 03 2004 Aug 10



100 V, 1 A NPN low V_{CEsat} (BISS) transistor

FEATURES

- SOT54 package
- Low collector-emitter saturation voltage V_{CEsat}
- High collector current capability: I_C and I_{CM}
- Higher efficiency leading to less heat generation.

APPLICATIONS

- Automotive 42 V power
- Telecom infrastructure
- General industrial applications
- Power management
 - DC/DC converters
 - Supply line switching
 - Battery charger
 - LCD backlighting.
- Peripheral drivers
 - Generic driver (e.g. lamps and LEDs)
 - Inductive load driver (e.g. relays, buzzers and motors).

DESCRIPTION

NPN low $V_{\mbox{CEsat}}$ BISS transistor in a SOT54 plastic package.

QUICK REFERENCE DATA

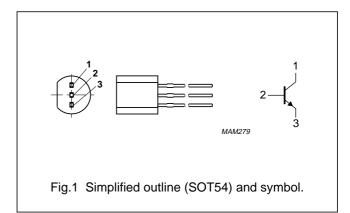
SYMBOL	PARAMETER	MAX.	UNIT	
V _{CEO}	collector-emitter voltage	100	V	
I _C	collector current (DC)	1	А	
I _{CM}	peak collector current	3	А	
R _{CEsat}	equivalent on-resistance 200		mΩ	

MARKING

TYPE NUMBER	MARKING CODE	
PBSS8110AS	S8110AS	

PINNING

PIN	DESCRIPTION	
1	collector	
2	base	
3	emitter	



ORDERING INFORMATION

TYPE NUMBER		PACKAGE			
ITPE NUMBER	NAME	DESCRIPTION	VERSION		
PBSS8110AS	_	plastic single-ended leaded (through hole) package; 3 leads			

PBSS8110AS

100 V, 1 A NPN low V_{CEsat} (BISS) transistor

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	-	120	V
V _{CEO}	collector-emitter voltage	open base	_	100	V
V _{EBO}	emitter-base voltage	open collector	_	5	V
I _C	collector current (DC)		_	1	А
I _{CM}	peak collector current	T _{j max}	-	3	A
I _B	base current (DC)		_	300	mA
P _{tot}	total power dissipation	$T_{amb} \le 25 \ ^{\circ}C$; note 1	_	830	mW
Tj	junction temperature		_	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C
T _{stg}	storage temperature		-65	+150	°C

Note

1. Device mounted on a FR4 printed-circuit board; single-sided copper; tinplated; standard footprint.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT	
R _{th(j-a)}	thermal resistance from junction to ambient	in free air; note 1	150	K/W	

Note

1. Device mounted on a FR4 printed-circuit board; single-sided copper; tinplated; standard footprint.

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CHARACTERISTICS

 $T_j = 25 \ ^{\circ}C$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CBO}	collector cut-off current	$V_{CB} = 80 \text{ V}; \text{ I}_{E} = 0$	-	-	100	nA
		V _{CB} = 80 V; I _E = 0; T _j = 150 °C	-	-	50	μA
I _{CES}	collector cut-off current	V _{CE} = 80 V; V _{BE} = 0	-	-	100	nA
I _{EBO}	emitter cut-off current	$V_{EB} = 4 \text{ V}; I_{C} = 0$	-	-	100	nA
h _{FE}	DC current gain	V _{CE} = 10 V; I _C = 1 mA	150	-	-	
		V _{CE} = 10 V; I _C = 250 mA	150	-	500	
		V _{CE} = 10 V; I _C = 0.5 A; note 1	100	-	-	
		V _{CE} = 10 V; I _C = 1 A; note 1	80	-	-	
V _{CEsat}	collector-emitter saturation	I _C = 100 mA; I _B = 10 mA	-	-	40	mV
	voltage	I _C = 500 mA; I _B = 50 mA	-	-	120	mV
		I _C = 1 A; I _B = 100 mA	-	-	200	mV
R _{CEsat}	equivalent on-resistance	$I_{C} = 1 \text{ A}; I_{B} = 100 \text{ mA}; \text{ note } 1$	-	165	200	mΩ
V _{BEsat}	base-emitter saturation voltage	I _C = 1 A; I _B = 100 mA; note 1	-	-	1.05	V
V _{BEon}	base-emitter turn-on voltage	V _{CE} = 10 V; I _C = 1 A	-	-	0.9	V
f _T	transition frequency	$V_{CE} = 10 \text{ V}; \text{ I}_{C} = 50 \text{ mA}; \text{ f} = 100 \text{ MHz}$	100	-	-	MHz
C _c	collector capacitance	$V_{CB} = 10 \text{ V}; I_E = I_e = 0; f = 1 \text{ MHz}$	_	_	7.5	pF

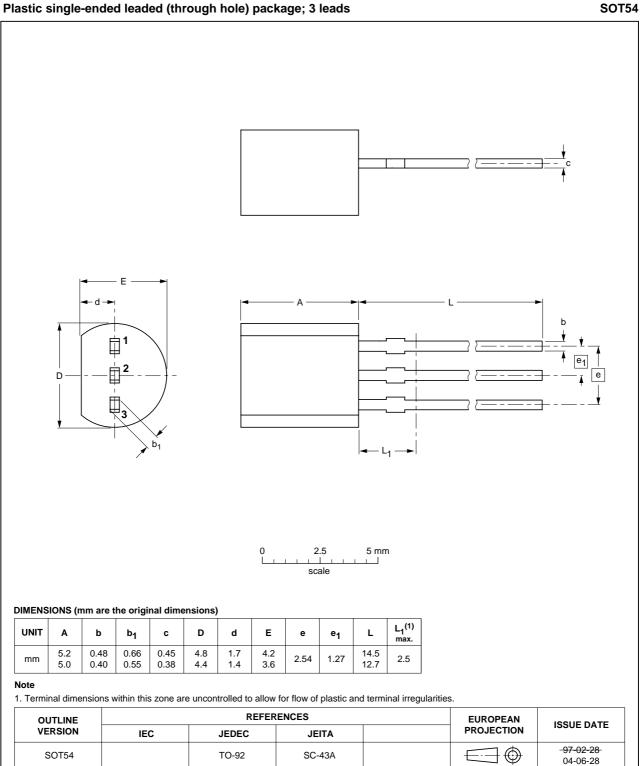
Note

1. Pulse test: $t_p \leq 300 \ \mu s; \ \delta \leq 0.02.$

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PACKAGE OUTLINE



Plastic single-ended leaded (through hole) package; 3 leads

100 V, 1 A NPN low V_{CEsat} (BISS) transistor

PBSS8110AS

DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾⁽³⁾	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

Notes

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- 2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.
- 3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

DEFINITIONS

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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